



HW 3729
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219.40440X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: PEARSON et al.
Serial No.: 09/964,746
Filed: September 28, 2001
For: METHOD AND STRUCTURE FOR IDENTIFYING LEAD-FREE
SOLDER
Group: 3729
Examiner: Carl J. Arbes

AMENDMENT

RECEIVED
MAY 19 2003
TECHNOLOGY CENTER R3700

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

May 12, 2003

Sir:

In response to the Office Action dated April 23, 2003, please amend the above-identified application as follows:

IN THE CLAIMS:

Please add new claims 31-35 as follows:

--31. The method of claim 6, wherein examining said heated predetermined solder pattern comprises determining that said solder is lead-free if said predetermined solder pattern after heating is in substantially a same pattern as said predetermined solder pattern before heating.--

--32. The method of claim 9, further comprising determining that said solder is lead-free if said predetermined solder pattern after heating is in substantially a same pattern as said predetermined solder pattern before heating.--

05/13/2003 SDENBOB1 00000110 09964746

01 FC:1201
02 FC:1202

84.00 OP
90.00 OP